Editorial

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Welcome to the second quarterly issue of year 2005.

Allow me to introduce to you our newest Associate Editor. He is Dr.Yu Gu who has a Ph.D. in Solid Mechanics from State Univ. of New York at Stony Brook and is employed by RF Micro Devices, Greensboro, NC.

Thermal management issues continue to motivate us to design better heat-sinks. Papers one through three offer several possible solutions to designing heat-sinks for ever shrinking sizes of electronic products.

Paper four deals with the thermal stresses faced by bimaterial structures - who hasn't experienced bonded semiconductor die or packaged die that have lifted from their substrates? Well, check this one out for possible leads!

Rapid curing of polymer dielectrics using microwave processing is covered in paper five.

In 1975 we felt lucky if we were able to print consistently thick film lines and spaces that were 250µm wide. In paper six, photoimageable thick film inks are used to print line widths of 30 µm and spaces of 100 µm - that is progress.

Currently, we are accepting paper submissions for review and possible publication in the Q4-2005 and beyond issues of this Journal. So, don't wait to send us your archival quality paper!

Regards,
Delip "Doug" Bokil
Editor-in-Chief